



N-Channel Enhancement Mode Power MOSFET

Description

The RM5N60S4 uses advanced trench technology and design to provide excellent $R_{\text{DS}(\text{ON})}$ with low gate charge. It can be used in a wide variety of applications.

General Features

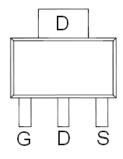
V_{DS} =60V,I_D =5A

 $R_{DS(ON)} < 55 m\Omega$ @ $V_{GS}=10V$ (Typ: $46 m\Omega$) $R_{DS(ON)} < 80m\Omega$ @ V_{GS} =4.5V (Typ: $60m\Omega$)

Schematic diagram

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free
- P/N suffix V means AEC-Q101 qualified, e.g:RM5N60S4V



SOT-223-3L view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quant	tity
6005	RM5N60S4	SOT-223-3L	Ø330mm	12mm	2500	units

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	5	А
Drain Current-Continuous(T _C =100 °C)	I _D (100°C)	3.5	А
Pulsed Drain Current	I _{DM}	20	А
Maximum Power Dissipation	P _D	2	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	62.5	°C/W

Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter Symbol Condition Min Typ Max Un							
Parameter	Symbol	Condition	IVIIII	тур	IVIAX	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	69	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA	

Gate-Body Leakage Current	I _{GSS}	$V_{GS}=\pm20V, V_{DS}=0V$	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.2	2	2.5	V	
Drain-Source On-State Resistance	В	V_{GS} =10V, I_D =4.5A		46	55	mΩ	
Diain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =4A		60	80	mΩ	
Forward Transconductance	g FS	V _{DS} =5V,I _D =4.5A	11	-	-	S	
Dynamic Characteristics (Note4)	·						
Input Capacitance	C _{lss}	\/ -25\/\/ -0\/		450		PF	
Output Capacitance	Coss	$V_{DS}=25V, V_{GS}=0V,$ $F=1.0MHz$		60		PF	
Reverse Transfer Capacitance	C _{rss}	F=1.0WI1Z		25		PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	4.7	-	nS	
Turn-on Rise Time	t _r	$V_{Ds} = 30V, I_{D} = 4.5A$	-	2.3	-	nS	
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{GEN} =3 Ω	-	15.7	-	nS	
Turn-Off Fall Time	t _f		-	1.9	-	nS	
Total Gate Charge	Q_g	$V_{DS}=30V, I_{D}=4.5A,$	-	8.5	-	nC	
Gate-Source Charge	Q _{gs}	$V_{DS}=30V,I_{D}=4.5A,$ $V_{GS}=10V$	-	1.6	-	nC	
Gate-Drain Charge	Q _{gd}	v GS= 10 v	-	2.2	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =5A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	5	Α	

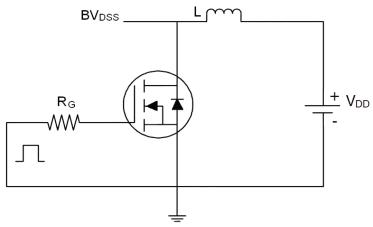
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
 Guaranteed by design, not subject to production

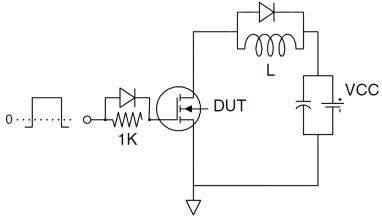


Test Circuit

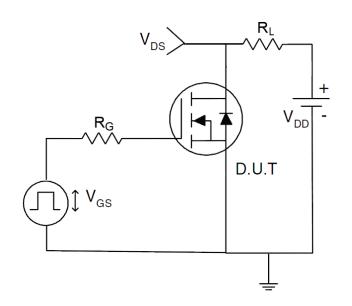
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit

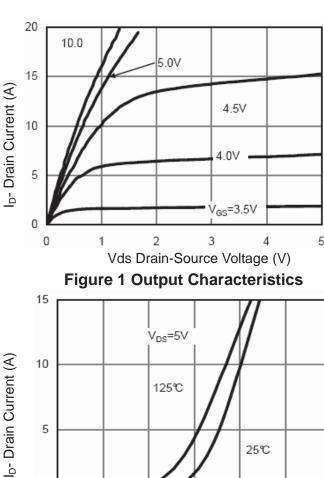


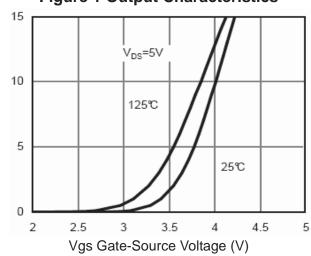
3) Switch Time Test Circuit

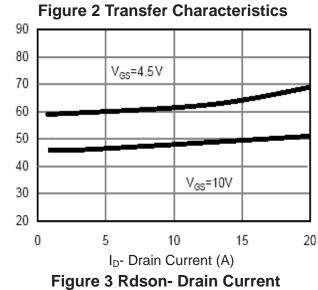




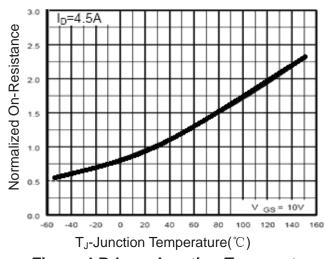
RATING AND CHARACTERISTICS CURVES (RM5N60S4)

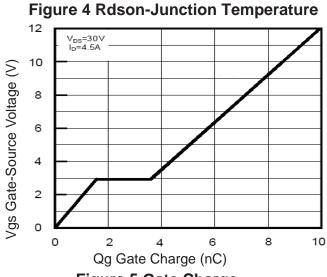






Rdson On-Resistance(mΩ)





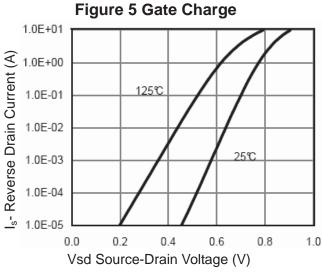


Figure 6 Source- Drain Diode Forward

RATING AND CHARACTERISTICS CURVES (RM5N60S4)

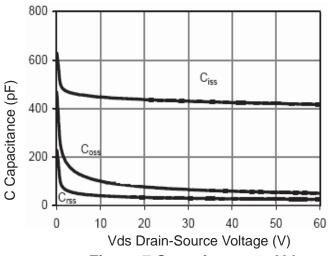


Figure 7 Capacitance vs Vds

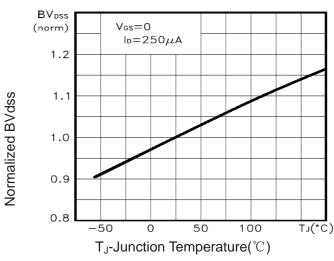


Figure 9 BV_{DSS} vs Junction Temperature

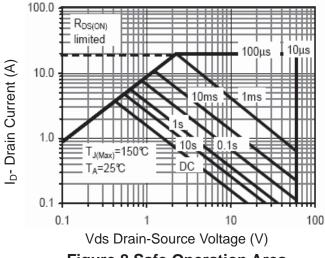


Figure 8 Safe Operation Area

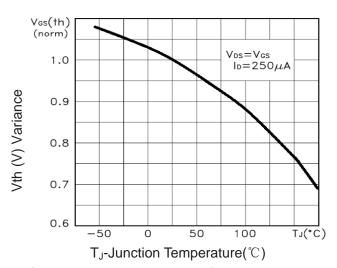


Figure 10 V_{GS(th)} vs Junction Temperature

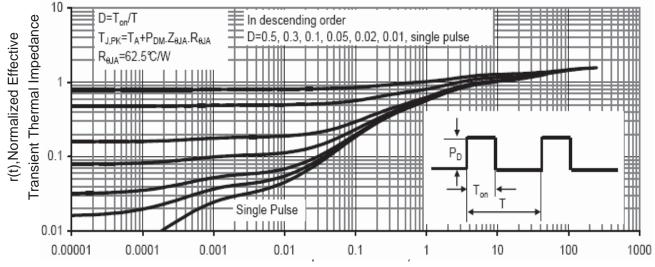
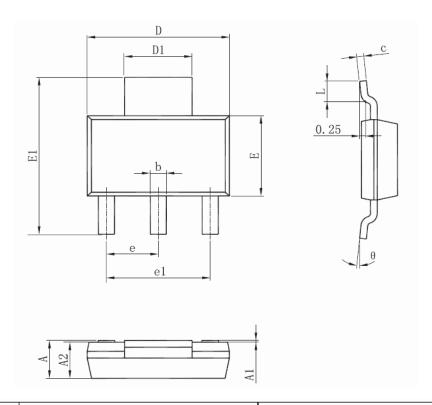


Figure 11 Normalized Maximum Transient Thermal Impedance



SOT-223-3L Package Information



C. mb a l	Dimensions Ir	n Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
С	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
е	2.300	(BSC)	0.091(BSC)
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
θ	0°	10°	0°	10°

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- $5. \ Controlling \ dimension \ is \ millimeter, \ converted \ inch \ dimensions \ are \ not \ necessarily \ exact.$



DISCLAIMER NOTICE

Rectron Inc reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. Rectron Inc or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on RECTRON data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. Rectron Inc does not assume any liability arising out of the application or use of any product or circuit.

Rectron products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of Rectron Inc. Customers using or selling Rectron components for use in such applications do so at their own risk and shall agree to fully indemnify Rectron Inc and its subsidiaries harmless against all claims, damages and expenditures.

